

### REMARKS

Applicant has carefully reviewed and considered the Office Action mailed on September 25, 2003. No claims are amended, canceled or added in this Response. Claims 1-29 remain pending in this application.

References are being submitted with this Response. Applicant makes no assertions or admissions whether these particular references are prior art. These references are also being submitted in an Information Disclosure Statement.

#### §112 Rejection of the Claims

Claims 3 and 7 were rejected under 35 USC § 112, first paragraph, as failing to comply with the written description requirement. The rejection stated: *The claims and specification have been amended to provide generic terminology but support for that generic terminology in the form of a trade sheet or other publication has not been provided making the amendment new matter.*

Applicant respectfully traverses the rejection and the assertion contained therein that the generic terminology is new matter. Applicant respectfully asserts that the original description originally conveys to one skilled in the relative art that the inventors had possession of the claimed invention.

The filed application used the trademark SILK in context of a low dielectric constant material. Applicant amended the application to include the generic term “spin-on low-k dielectric resin” in reference to the trademark SILK. In support of the Applicant’s position that one skilled in the relative art would understand that the inventors had possession of the claimed subject matter, the following references are submitted with this Response:

Martin, Steven J., “The Invention and Development of a Low-Dielectric Constant Polymer for the Fabrication of Integrated Circuit Interconnect”, Seminar Department of Chemical Engineering North Carolina State University, April 9, 2001.

The DOW Chemical Company, SiLK\* D Semiconductor Dielectric Resin, date unknown (www.silk.dow.com).

The DOW Chemical Company, SiLK\* J Semiconductor Dielectric Resin, date unknown  
([www.silk.dow.com](http://www.silk.dow.com)).

The filed application used the trademark NANOGLASS in context of a low dielectric constant material. Applicant amended the application to include the term “porous siloxane-based polymer” in reference to the trademark NANOGLASS. In support of the Applicant’s position that one skilled in the relative art would understand that the inventors had possession of the claimed subject matter, the following reference is submitted with this Response:

Zhang et al., “Nanoglass<sup>TM</sup> E Copper Damascene Processing for Etch, Clean, and CMP”,  
2001 ([www.electronicmaterials.com/star\\_center/technical\\_papers.html](http://www.electronicmaterials.com/star_center/technical_papers.html)).

*Allowable Subject Matter*

Claims 1-29 were indicated to be allowable if rewritten to overcome the rejection(s) under 35 USC § 112 set forth in the Office Action. Applicant notes with thanks that, in the Office Action Summary, claims 1, 2, 4-6 and 8-29 were indicated to be allowed.

Conclusion

Applicant respectfully submits that the claims are in condition for allowance and notification to that effect is earnestly requested. The Examiner is invited to telephone Applicant's attorney (612) 373-6960 to facilitate prosecution of this application.

If necessary, please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

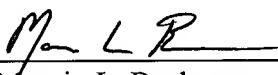
Respectfully submitted,

KIE Y. AHN ET AL.

By their Representatives,

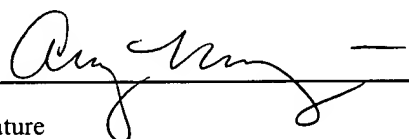
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Date 11-21-03

By   
Marvin L. Beekman  
Reg. No. 38,377

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Mail Stop RCE, Commissioner of Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 21st day of November, 2003.

Amy Moriarty  
Name

  
Signature